

FEATURES

Four 14-Bit DACs in One Package
Voltage Outputs
Separate Offset Adjust for Each Output
Reference Range of ± 5 V
Maximum Output Voltage Range of ± 10 V
Clear Function to User-Defined Code
44-Pin MQFP Package

APPLICATIONS

Process Control
Automatic Test Equipment
General Purpose Instrumentation

GENERAL DESCRIPTION

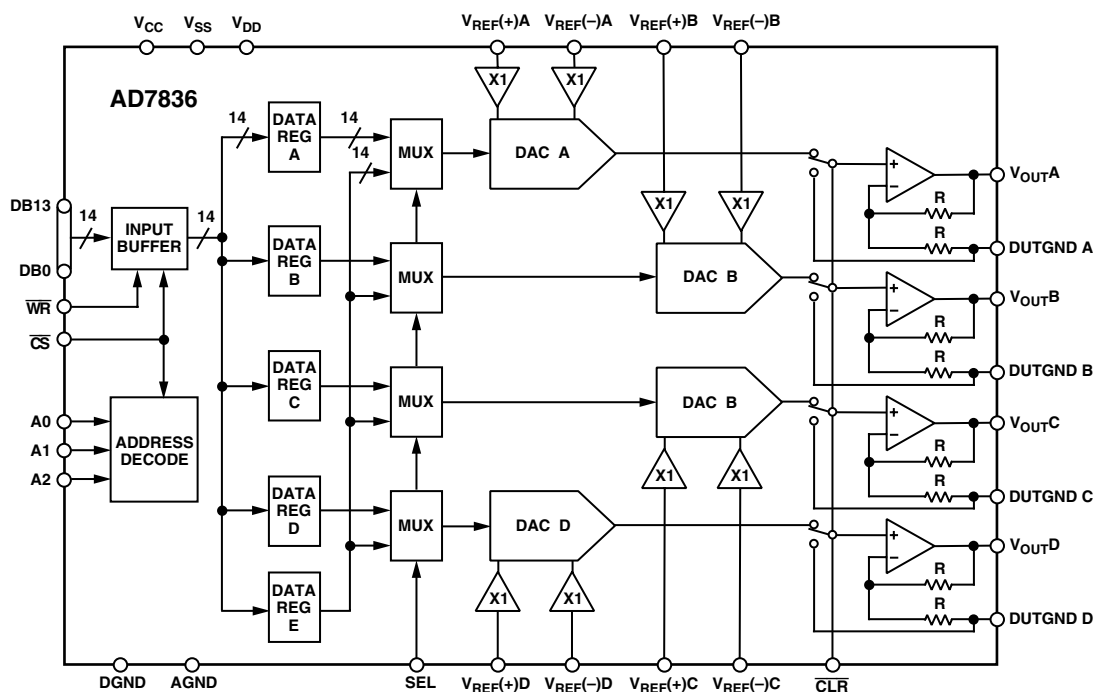
The AD7836 contains four 14-bit DACs on one monolithic chip. It has output voltages with a full-scale range of ± 10 V from reference voltages of ± 5 V.

The AD7836 accepts 14-bit parallel loaded data from the external bus into one of the input latches under the control of the WR, CS and DAC channel address pins, A0–A2.

The DAC outputs are updated individually, on reception of new data. In addition, the SEL input can be used to apply the user programmed value in DAC Register E to all DACs, thus setting all DAC output voltages to the same level. The contents of the DAC data registers are not affected by the SEL input.

Each DAC output is buffered with a gain of two amplifier into which an external DAC offset voltage can be inserted via the DUTGNDx pins.

The AD7836 is available in a 44-lead MQFP package.

FUNCTIONAL BLOCK DIAGRAM


REV. A

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AD7836—SPECIFICATIONS

($V_{CC} = +5\text{ V} \pm 5\%$; $V_{DD} = +15\text{ V} \pm 5\%$; $V_{SS} = -15\text{ V} \pm 5\%$; $AGND = DGND = DUTGND = 0\text{ V}$; $R_L = 5\text{ k}\Omega$ and $C_L = 50\text{ pF}$ to GND , $T_A^1 = T_{MIN}$ to T_{MAX} , unless otherwise noted)

Parameter	A	Units	Test Conditions/Comments
ACCURACY			
Resolution	14	Bits	
Relative Accuracy	± 2	LSB max	
Differential Nonlinearity	± 0.9	LSB max	Guaranteed Monotonic Over Temperature
Full-Scale Error	± 8	LSB max	$V_{REF(+)} = +5\text{ V}$, $V_{REF(-)} = -5\text{ V}$. Typically within ± 1 LSB
Zero-Scale Error	± 8	LSB max	$V_{REF(+)} = +5\text{ V}$, $V_{REF(-)} = -5\text{ V}$. Typically within ± 1 LSB
Gain Error	± 2	mV typ	$V_{REF(+)} = +5\text{ V}$, $V_{REF(-)} = -5\text{ V}$
Gain Temperature Coefficient ²	20	ppm FSR/ $^{\circ}\text{C}$ typ	
	40	ppm FSR/ $^{\circ}\text{C}$ max	
DC Crosstalk ²	50	μV max	See Terminology. $R_L = 5\text{ k}\Omega$
REFERENCE INPUTS			
DC Input Resistance	100	M Ω typ	
Input Current	± 1	μA max	Per Input. Typically $\pm 20\text{ nA}$
$V_{REF(+)}$ Range	0/+5	V min/max	
$V_{REF(-)}$ Range	-5/0	V min/max	
$[V_{REF(+)} - V_{REF(-)}]$	2/10	V min/max	For Specified Performance. Can Go as Low as 0 V, but Performance Not Guaranteed
OUTPUT CHARACTERISTICS			
Output Voltage Swing	± 10	V min	$2 \times (V_{REF(-)} + [V_{REF(+)} - V_{REF(-)}] \cdot D) - V_{DUTDGN}$
Short Circuit Current	25	mA max	
Resistive Load	5	k Ω min	To 0 V
Capacitive Load	50	pF max	To 0 V
DIGITAL INPUTS			
V_{INH} , Input High Voltage	2.4	V min	
V_{INL} , Input Low Voltage	0.8	V max	
I_{INH} , Input Current	± 10	μA max	Total for All Pins
C_{IN} , Input Capacitance	10	pF max	
POWER REQUIREMENTS			
V_{CC}	5.0	V nom	$\pm 5\%$ for Specified Performance
V_{DD}	15.0	V nom	$\pm 5\%$ for Specified Performance
V_{SS}	-15.0	V nom	$\pm 5\%$ for Specified Performance
Power Supply Sensitivity			
$\Delta\text{Full Scale}/\Delta V_{DD}$	110	dB typ	
$\Delta\text{Full Scale}/\Delta V_{SS}$	100	dB typ	
I_{CC}	0.5	mA max	$V_{INH} = V_{CC}$, $V_{INL} = DGND$. Dynamic Current
	8	mA max	$V_{INH} = 2.4\text{ V}$ min, $V_{INL} = 0.8\text{ V}$ max
I_{DD}	14	mA max	Outputs Unloaded. Typically 7 mA
I_{SS}	14	mA max	Outputs Unloaded. Typically 7 mA

AC PERFORMANCE CHARACTERISTICS (These characteristics are included for Design Guidance and are not subject to production testing.)

Parameter	A	Units	Test Conditions/Comments
DYNAMIC PERFORMANCE			
Output Voltage Settling Time	16	μs typ	Full-Scale Change to $\pm 1/2$ LSB. DAC Latch Contents Alternately Loaded with All 0s and All 1s
Digital-to-Analog Glitch Impulse	150	nV-s typ	Measured with $V_{REF(+)} = +5\text{ V}$, $V_{REF(-)} = -5\text{ V}$. DAC Latch Alternately Loaded with 1FFF Hex and 2000 Hex. Not Dependent on Load Conditions
DC Output Impedance	0.3	Ω max	See Terminology
Channel-to-Channel Isolation	115	dB typ	See Terminology
DAC-to-DAC Crosstalk	10	nV-s typ	See Terminology
Digital Crosstalk	10	nV-s typ	Feedthrough to DAC Output Under Test Due to Change in Digital Input Code to Another Converter
Digital Feedthrough	0.2	nV-s typ	Effect of Input Bus Activity on DAC Output Under Test
Output Noise Spectral Density @ 1 kHz	40	nV/ $\sqrt{\text{Hz}}$ typ	All 1s Loaded to DAC. $V_{REF(+)} = V_{REF(-)} = 0\text{ V}$

NOTES

¹Temperature range for A Version: -40°C to $+85^{\circ}\text{C}$

²Guaranteed by design.

Specifications subject to change without notice.

TIMING SPECIFICATIONS¹ ($V_{CC} = +5\text{ V} \pm 5\%$; $V_{DD} = +15\text{ V} \pm 5\%$; $V_{SS} = -15\text{ V} \pm 5\%$; $AGND = DGND = 0\text{ V}$)

Parameter	Limit at T_{MIN} , T_{MAX}	Units	Description
t_1	15	ns min	A0, A1, A2 to WR Setup Time
t_2	0	ns min	A0, A1, A2 to WR Hold Time
t_3	0	ns min	CS to WR Setup Time
t_4	0	ns min	WR to CS Hold Time
t_5	44	ns min	WR Pulsewidth
t_6	15	ns min	Data Setup Time
t_7	4.5	ns min	Data Hold Time
t_8	44	ns min	WR Pulse Interval
t_9	16	$\mu\text{s typ}$	Settling Time
t_{10}	300	ns max	CLR Pulse Activation Time

NOTES

¹All input signals are specified with $t_r = t_f = 5\text{ ns}$ (10% to 90% of 5 V) and timed from a voltage level of 1.6 V.

²Rise and fall times should be no longer than 50 ns.

Specifications subject to change without notice.

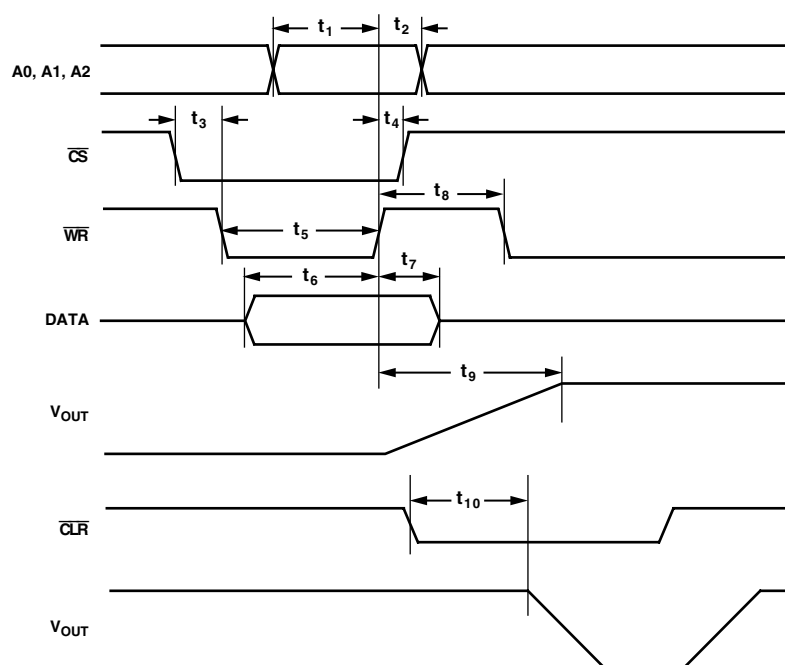


Figure 1. Timing Diagram

AD7836

ABSOLUTE MAXIMUM RATINGS¹

(T_A = +25°C unless otherwise noted)

V _{CC} to DGND	−0.3 V, +7 V or V _{DD} + 0.3 V (Whichever Is Lower)
V _{DD} to AGND	−0.3 V, +17 V
V _{SS} to AGND	+0.3 V, −17 V
AGND to DGND	−0.3 V, +0.3 V
Digital Inputs to DGND	−0.3 V, V _{CC} + 0.3 V
V _{REF} (+) to V _{REF} (−)	−0.3 V, +18 V
V _{REF} (+) to AGND	V _{SS} − 0.3 V, V _{DD} + 0.3 V
V _{REF} (−) to AGND	V _{SS} − 0.3 V, V _{DD} + 0.3 V
DUTGND to AGND	V _{SS} − 0.3 V, V _{DD} + 0.3 V
V _{OUT} (A–D) to AGND	V _{SS} − 0.3 V, V _{DD} + 0.3 V
Operating Temperature Range	
Industrial (A Version)	−40°C to +85°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature	+150°C

MQFP Package, Power Dissipation	480 mW
θ _{JA} Thermal Impedance	95°C/W
Lead Temperature, Soldering	
Vapor Phase (60 sec)	+215°C
Infrared (15 sec)	+220°C

NOTES

¹Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

²Transient currents of up to 100 mA will not cause SCR latch-up.

ORDERING GUIDE

Model	Temperature Range	Linearity Error (LSBs)	DNL (LSBs)	Package Option*
AD7836AS	−40°C to +85°C	±2	±0.9	S-44

*S = Plastic Quad Flatpack (MQFP).

CAUTION

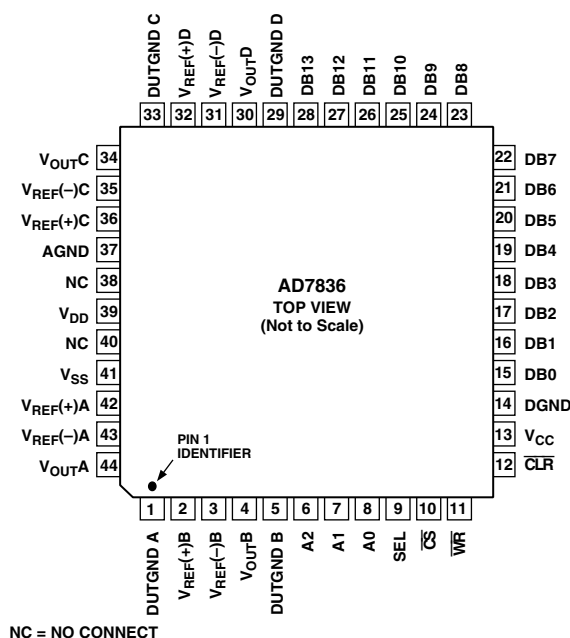
ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the AD7836 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



PIN DESCRIPTION

Pin Mnemonic	Description
V _{CC}	Logic Power Supply; +5 V $\pm$ 5%.
V _{SS}	Negative Analog Power Supply; -15 V $\pm$ 5%.
V _{DD}	Positive Analog Power Supply; +15 V $\pm$ 5%.
DGND	Digital Ground.
AGND	Analog Ground.
V _{REF} (+)A, V _{REF} (-)A	Reference Inputs for DAC A. These reference voltages are referred to AGND.
V _{REF} (+)B, V _{REF} (-)B	Reference Inputs for DAC B. These reference voltages are referred to AGND.
V _{REF} (+)C, V _{REF} (-)C	Reference Inputs for DAC C. These reference voltages are referred to AGND.
V _{REF} (+)D, V _{REF} (-)D	Reference Inputs for DAC D. These reference voltages are referred to AGND.
V _{OUT} A . . . V _{OUT} D	DAC Outputs.
CS	Level-Triggered Chip Select Input (active low). The device is selected when this input is low.
DB0 . . . DB13	Parallel Data Inputs. The AD7836 can accept a straight 14-bit parallel word on DB0 to DB13 where DB13 is the MSB and DB0 is the LSB.
A0, A1, A2	Address inputs. A0, A1 and A2 are decoded to select one of the five input latches for a data transfer.
CLR	Asynchronous Clear Input (level sensitive, active low). When this input is low, all analog outputs are switched to the externally set potential on the DUTGND pin. The contents of data registers A to E are not affected when the CLR pin is taken low. When CLR is brought back high, the DAC outputs revert back to their original outputs as determined by the data in their data registers.
WR	Level-Triggered Write Input (active low), when active and used in conjunction with CS to write data to the AD7836 input buffer. Data is latched into the selected data register on the rising edge of WR.
DUTGND A	Device Sense Ground for DAC A. Vout A is referenced to the voltage applied to this pin.
DUTGND B	Device Sense Ground for DAC B. Vout B is referenced to the voltage applied to this pin.
DUTGND C	Device Sense Ground for DAC C. Vout C is referenced to the voltage applied to this pin.
DUTGND D	Device Sense Ground for DAC D. Vout D is referenced to the voltage applied to this pin.
SEL	Select pin, active high level triggered input. When the SEL input is high, the user programmed value in DATAREG E will be loaded into all DAC registers and the DAC outputs updated accordingly. The contents of the other DATA REGs (A–D) will not be affected by the SEL pin.

PIN CONFIGURATION



AD7836

TERMINOLOGY

Relative Accuracy

Relative accuracy or endpoint linearity is a measure of the maximum deviation from a straight line passing through the endpoints of the DAC transfer function. It is measured after adjusting for zero error and full-scale error and is normally expressed in Least Significant Bits or as a percentage of full-scale reading.

Differential Nonlinearity

Differential nonlinearity is the difference between the measured change and the ideal 1 LSB change between any two adjacent codes. A specified differential nonlinearity of 1 LSB maximum ensures monotonicity.

DC Crosstalk

Although the common input reference voltage signals are internally buffered, small IR drops in the individual DAC reference inputs across the die can mean that an update to one channel can produce a dc output change in one or other of the channel outputs.

The four DAC outputs are buffered by op amps that share common V_{DD} and V_{SS} power supplies. If the dc load current changes in one channel (due to an update), this can result in a further dc change in one or other channel outputs. This effect is most obvious at high load currents and reduces as the load currents are reduced. With high impedance loads the effect is virtually unmeasurable.

Output Voltage Settling Time

This is the amount of time it takes for the output to settle to a specified level for a full-scale input change.

Digital-to-Analog Glitch Impulse

This is the amount of charge injected into the analog output when the inputs change state. It is specified as the area of the glitch in nV-secs. It is measured with $V_{REF(+)} = +5\text{ V}$ and $V_{REF(-)} = -5\text{ V}$ and the digital inputs toggled between 1FFFHEX and 8000H.

Channel-to-Channel Isolation

Channel-to-channel isolation refers to the proportion of input signal from one DAC's reference input that appears at the output of the other DAC. It is expressed in dBs.

DAC-to-DAC Crosstalk

DAC-to-DAC crosstalk is defined as the glitch impulse that appears at the output of one converter due to both the digital change and subsequent analog O/P change at another converter. It is specified in nV-s.

Digital Crosstalk

The glitch impulse transferred to the output of one converter due to a change in digital input code to the other converter is defined as the digital crosstalk and is specified in nV-s.

Digital Feedthrough

When the device is not selected, high frequency logic activity on the device's digital inputs can be capacitively coupled both across and through the device to show up as noise on the V_{OUT} pins. This noise is digital feedthrough.

DC Output Impedance

This is the effective output source resistance. It is dominated by package lead resistance.

Full-Scale Error

This is the error in DAC output voltage when all 1s are loaded into the DAC latch. Ideally the output voltage, with all 1s loaded into the DAC latch, should be $2 V_{REF(+)} - 1\text{ LSB}$. Full-scale error does not include zero-scale error.

Zero-Scale Error

Zero-scale error is the error in the DAC output voltage when all 0s are loaded into the DAC latch. Ideally the output voltage, with all 0s in the DAC latch should be equal to $2 V_{REF(-)}$. Zero-scale error is mainly due to offsets in the output amplifier.

Gain Error

Gain Error is defined as (Full-Scale Error) – (Zero-Scale Error).

GENERAL DESCRIPTION

DAC Architecture—General

Each channel consists of a segmented 14-bit R-2R voltage-mode DAC. The full-scale output voltage range is equal to twice the reference span of $V_{REF(+)} - V_{REF(-)}$. The DAC coding is straight binary; all 0s produces an output of $2 V_{REF(-)}$; all 1s produces an output of $2 V_{REF(+)} - 1\text{ LSB}$.

The analog output voltage of each DAC channel reflects the contents of its own DAC latch. Data is transferred from the external bus to the input register of each DAC latch on a per channel basis. The AD7836 has a feature whereby using the A2 pin, data can be transferred from the input data bus to all four input registers simultaneously.

Bringing the CLR line low switches all the signal outputs, V_{OUTA} to V_{OUTD} , to the voltage level on the DUTGND pin. When CLR signal is brought back high the output voltages from the DACs will reflect the data stored in the relevant DAC registers.

Data Loading to the AD7836

Data is loaded into the AD7836 in straight parallel 14-bit wide words.

The DAC output voltages, V_{OUTA} – V_{OUTD} are updated to reflect new data in the DAC input registers.

The actual DAC input register that is being written to is determined by the logic levels present on the device's address lines, as shown in Table I.

Table I. Address Line Truth Table

A2	A1	A0	DAC Selected
0	0	0	DATA REG A (DAC A)
0	0	1	DATA REG B (DAC B)
0	1	0	DATA REG C (DAC C)
0	1	1	DATA REG D (DAC D)
1	0	0	DATA REG E
1	1	1	DATA REG A–D

Typical Performance Characteristics—AD7836

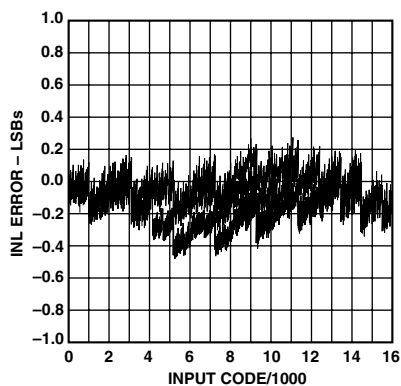


Figure 2. Typical INL Plot

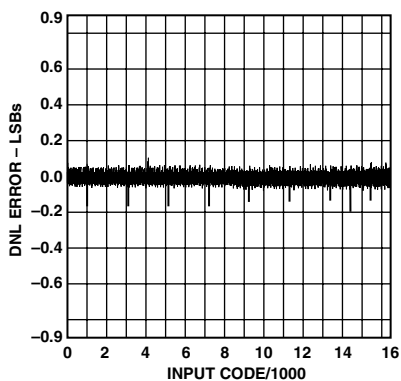


Figure 3. Typical DNL Plot

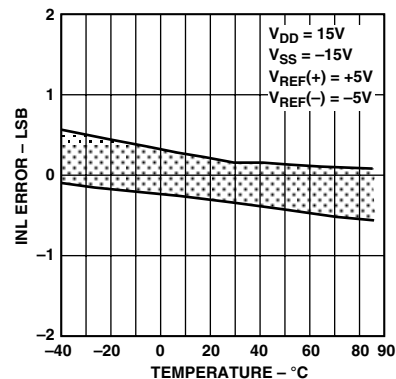


Figure 4. Typical INL Error vs. Temperature

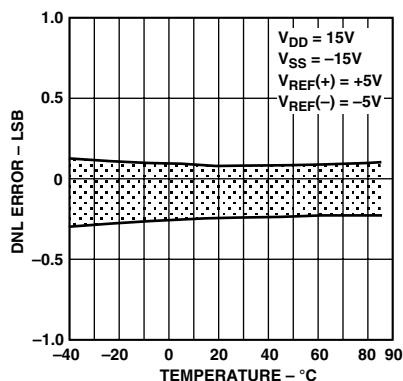


Figure 5. Typical DNL Error vs. Temperature

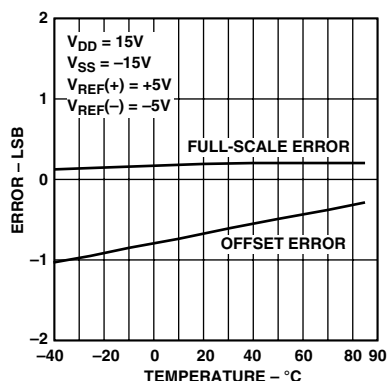


Figure 6. Offset and Full-Scale Error vs. Temperature

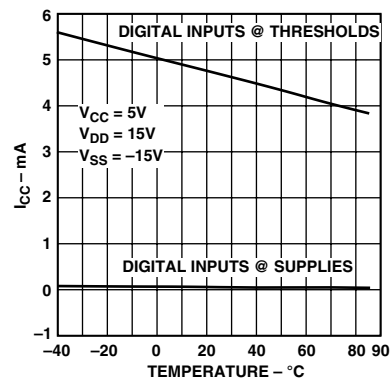


Figure 7. I_{CC} vs. Temperature

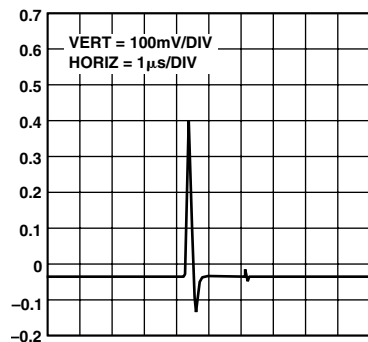


Figure 8. Typical Digital/Analog Glitch Impulse

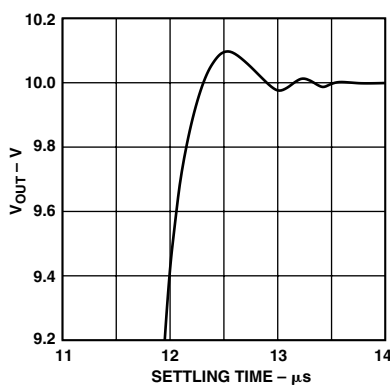


Figure 9. Settling Time (+)

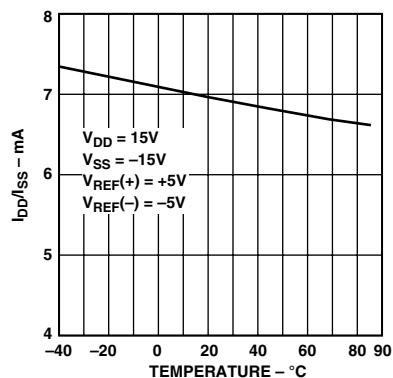


Figure 10. I_{DD}/I_{SS} vs. Temperature

AD7836

Unipolar Configuration

Figure 11 shows the AD7836 in the unipolar binary circuit configuration. The $V_{REF}(+)$ input of the DAC is driven by the AD586, a +5 V reference. $V_{REF}(-)$ is tied to ground. Table II gives the code table for unipolar operation of the AD7836. Other suitable references include the REF02, a precision 5 V reference, and the REF195, a low dropout, micropower precision +5 V reference.

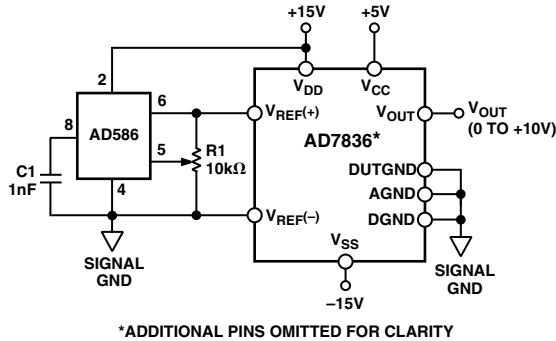


Figure 11. Unipolar +5 V Operation

Offset and gain may be adjusted in Figure 2 as follows: To adjust offset, disconnect the $V_{REF}(-)$ input from 0 V, load the DAC with all 0s and adjust the $V_{REF}(-)$ voltage until $V_{OUT} = 0$ V. For gain adjustment, the AD7836 should be loaded with all 1s and R1 adjusted until $V_{OUT} = 10$ V (16383/16384) = 9.999389.

Many circuits will not require these offset and gain adjustments. In these circuits R1 can be omitted. Pin 5 of the AD586 may be left open circuit and Pin 2 ($V_{REF}(-)$) of the AD7836 tied to 0 V.

Table II. Code Table for Unipolar Operation

Binary Number in DAC Latch				Analog Output (V_{OUT})
MSB		LSB		
11	1111	1111	1111	$2 V_{REF} (16383/16384)$ V
10	0000	0000	0000	$2 V_{REF} (8192/16384)$ V
01	1111	1111	1111	$2 V_{REF} (8191/16384)$ V
00	0000	0000	0001	$2 V_{REF} (1/16384)$ V
00	0000	0000	0000	0 V

NOTE

$V_{REF} = V_{REF}(+)$; $V_{REF}(-) = 0$ V for unipolar operation.
For $V_{REF}(+) = +5$ V, 1 LSB = $+10$ V/ 2^{14} = $+10$ V/16384 = 610 μ V.

Bipolar Configuration

Figure 12 shows the AD7836 set up for ± 10 V operation. The AD588 provides precision ± 5 V tracking outputs that are fed to the $V_{REF}(+)$ and $V_{REF}(-)$ inputs of the AD7836. The code table for bipolar operation of the AD7836 is shown in Table III.

In Figure 12, full-scale and bipolar zero adjustments are provided by varying the gain and balance on the AD588. R2 varies the gain on the AD588 while R3 adjusts the offset of both the +5 V and -5 V outputs together with respect to ground.

For bipolar-zero adjustment, the DAC is loaded with 1000 . . . 0000 and R3 is adjusted until $V_{OUT} = 0$ V. Full scale is adjusted by loading the DAC with all 1s and adjusting R2 until $V_{OUT} = 10$ (8191/8192) V = 9.998779 V.

When bipolar-zero and full-scale adjustment are not needed, R2 and R3 can be omitted. Pin 12 on the AD588 should be connected to Pin 11 and Pin 5 should be left floating.

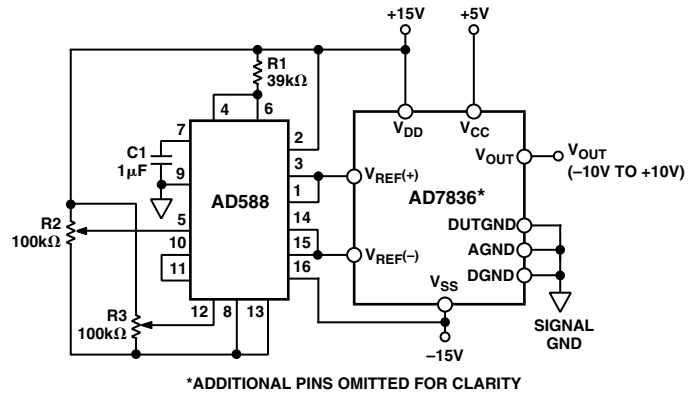


Figure 12. Bipolar ± 5 V Operation

Table III. Code Table for Bipolar Operation

Binary Number in DAC Latch				Analog Output (V_{OUT})
MSB		LSB		
11	1111	1111	1111	$2[V_{REF}(-) + V_{REF} (16383/16384)]$ V
10	0000	0000	0001	$2[V_{REF}(-) + V_{REF} (8193/16384)]$ V
10	0000	0000	0000	$2[V_{REF}(-) + V_{REF} (8192/16384)]$ V
01	1111	1111	1111	$2[V_{REF}(-) + V_{REF} (8191/16384)]$ V
00	0000	0000	0001	$2[V_{REF}(-) + V_{REF} (1/16384)]$ V
00	0000	0000	0000	$2[V_{REF}(-)]$ V

NOTE

$V_{REF} = (V_{REF}(+) - V_{REF}(-))$.

For $V_{REF}(+) = +5$ V, and $V_{REF}(-) = -5$ V, $V_{REF} = 10$ V, 1 LSB = $2 V_{REF} V/2^{14}$ = 20 V/16384 = 1220 μ V.

CONTROLLED POWER-ON OF THE OUTPUT STAGE

A block diagram of the output stage of the AD7836 is shown in Figure 13. It is capable of driving a load of 5 k Ω in parallel with 50 pF. G_1 to G_6 are transmission gates that are used to control the power on voltage present at V_{OUT} . On power up G_1 and G_2 are also used in conjunction with the CLR input to set V_{OUT} to the user defined voltage present at the DUTGND pin. When CLR is taken back high the DAC outputs reflect the data in the DAC registers.

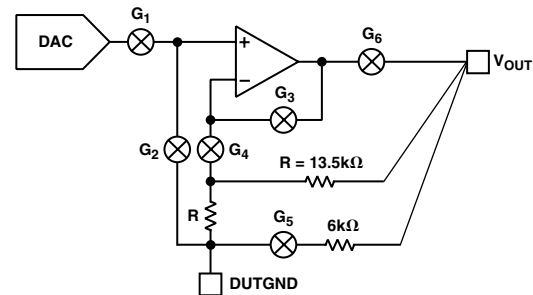


Figure 13. Block Diagram of AD7836 Output Stage

Power-On with CLR Low

The output stage of the AD7836 has been designed to allow output stability during power-on. If CLR is kept low during power-on, then just after power is applied to the AD7836, the situation is as depicted in Figure 14. G_1 , G_4 and G_6 are open while G_2 , G_3 and G_5 are closed.

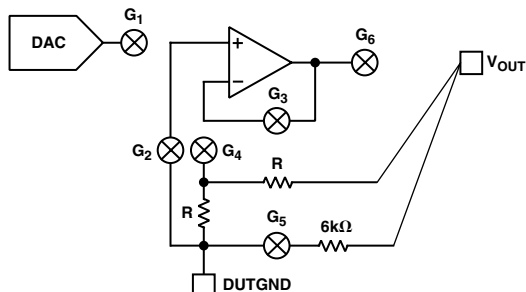


Figure 14. Output Stage with $V_{DD} < 10\text{ V}$

V_{OUT} is kept within a few hundred millivolts of DUTGND via G_5 and a $6\text{k}\Omega$ resistor. This thin-film resistor is connected in parallel with the gain resistors of the output amplifier. The output amplifier is connected as a unity gain buffer via G_3 , and the DUTGND voltage is applied to the buffer input via G_2 . The amplifier's output is thus at the same voltage as the DUTGND pin. The output stage remains configured as in Figure 14 until the voltage at V_{DD} and V_{SS} reaches approximately $\pm 10\text{ V}$. By now the output amplifier has enough headroom to handle signals at its input and has also had time to settle. The internal power-on circuitry opens G_3 and G_5 and closes G_4 and G_6 . This situation is shown in Figure 15. Now the output amplifier is configured in its noise gain configuration via G_4 and G_6 . The DUTGND voltage is still connected to the noninverting input via G_2 and this voltage appears at V_{OUT} .

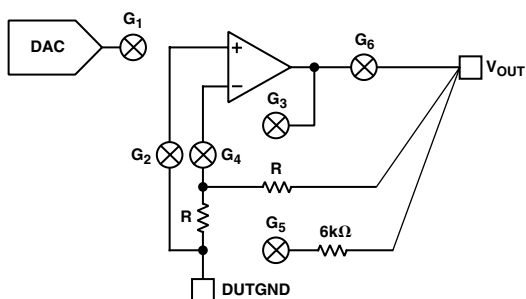


Figure 15. Output Stage with $V_{DD} > 10\text{ V}$ and $\overline{\text{CLR}}$ Low

V_{OUT} has been disconnected from the DUTGND pin by the opening of G_5 but will track the voltage present at DUTGND via the configuration shown in Figure 15.

When CLR is taken back high, the output stage is configured as shown in Figure 16. The internal control logic closes G_1 and opens G_2 . The output amplifier is connected in a noninverting gain of two configuration. The voltage that appears on the V_{out} pins is determined by the data present in the DAC registers. To set all output voltages to the same known state, a write to DATA REG E with the SEL pin high allows all DAC registers to be updated with the same data.

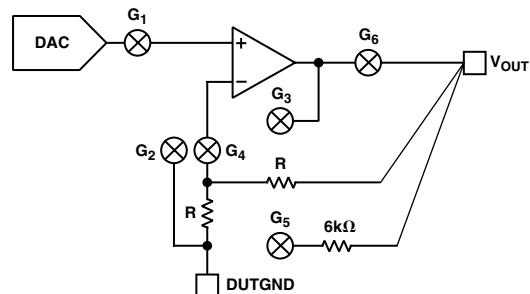


Figure 16. Output Stage After $\overline{\text{CLR}}$ Is Taken High

Power-On with CLR High

If CLR is high on the application of power to the device, the output stages of the AD7836 are configured as in Figure 17 while V_{DD}/V_{SS} are less than $\pm 10\text{ V}$. G_1 is closed and G_2 is open thereby connecting the output of the DAC to the input of its output amplifier. G_3 and G_5 are closed while G_4 and G_6 are open thus connecting the output amplifier as a unity gain buffer. V_{OUT} is connected to DUTGND via G_5 through a $6\text{ k}\Omega$ resistor until V_{DD} and V_{SS} reach approximately $\pm 10\text{ V}$.

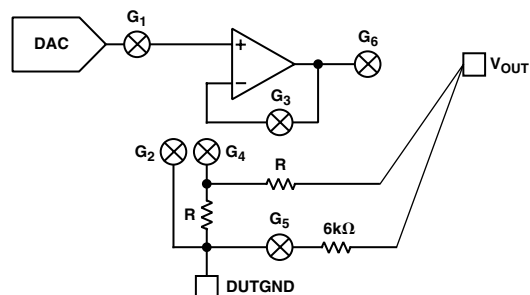


Figure 17. Output Stage Powering Up with $\overline{\text{CLR}}$ High While $V_{DD}/V_{SS} < \pm 10\text{ V}$

When the supplies reach $\pm 10\text{ V}$, the internal power on circuitry opens G_3 and G_5 and closes G_4 and G_6 configuring the output stage as shown in Figure 18.

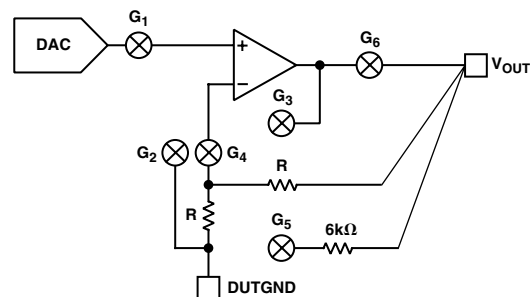


Figure 18. Output Stage Powering Up with $\overline{\text{CLR}}$ High When $V_{DD}/V_{SS} > \pm 10\text{ V}$

AD7836

DUTGND Voltage Range

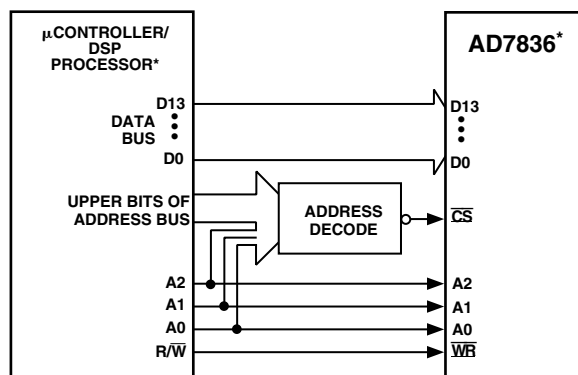
During power-on, the V_{OUT} pins of the AD7836 are connected to the relevant DUTGND pins via G_6 and the 6 k Ω thin-film resistor. The DUTGND potential must obey the max ratings at all times. Thus, the voltage at DUTGND must always be within the range $V_{SS} - 0.3$ V, $V_{DD} + 0.3$ V. However, in order that the voltages at the V_{OUT} pins of the AD7836 stay within ± 2 V of the relevant DUTGND potential during power-on, the voltage applied to DUTGND should also be kept within the range $AGND - 2$ V, $AGND + 2$ V.

Once the AD7836 has powered on and the on-chip amplifiers have settled, any voltage that is now applied to the DUTGND pin is subtracted from the DAC output which has been gained up by a factor of two. Thus, for specified operation, the maximum voltage that can be applied to the DUTGND pin increases to the maximum allowable $2 \times V_{REF}(+)$ voltage, and the minimum voltage that can be applied to DUTGND is the minimum $2 \times V_{REF}(-)$ voltage. After the AD7836 has fully powered on, the outputs can track any DUTGND voltage within this minimum/maximum range.

MICROPROCESSOR INTERFACING

Interfacing the AD7836—16-Bit Interface

The AD7836 can be interfaced to a variety of 16-bit microcontrollers or DSP processors. Figure 19 shows the AD7836 interfaced to a generic 16-bit microcontroller/DSP processor. The lower address lines from the processor are connected to A0, A1 and A2 on the AD7836 as shown. The upper address lines are decoded to provide a chip select signal for the AD7836. They are also decoded (in conjunction with the lower address lines if need be) to provide a SEL signal. The fast interface timing of the AD7836 allows direct interface to a wide variety of microcontrollers and DSPs as shown in Figure 19.



*ADDITIONAL PINS OMITTED FOR CLARITY

Figure 19. AD7836 Parallel Interface

APPLICATIONS

Power Supply Bypassing and Grounding

In any circuit where accuracy is important, careful consideration of the power supply and ground return layout helps to ensure the rated performance. The printed circuit board on which the AD7836 is mounted should be designed such that the analog and digital sections are separated and confined to certain areas of the board. This facilitates the use of ground planes that can be separated easily. A minimum etch technique is generally best for ground planes as it gives the best shielding. Digital and analog ground planes should only be joined at one place. If the AD7836 is the only device requiring an AGND to DGND connection, then the ground planes should be connected at the AGND and DGND pins of the AD7836. If the AD7836 is in a system where multiple devices require an AGND to DGND connection, the connection should still be made at one point only, a star ground point which should be established as close as possible to the AD7836.

Digital lines running under the device should be avoided as these will couple noise onto the die. The analog ground plane should be allowed to run under the AD7836 to avoid noise coupling. The power supply lines of the AD7836 should use as large a trace as possible to provide low impedance paths and reduce the effects of glitches on the power supply line. Fast switching signals like clocks should be shielded with digital ground to avoid radiating noise to other parts of the board and should never be run near the analog inputs.

Avoid crossover of digital and analog signals. Traces on opposite sides of the board should run at right angles to each other. This reduces the effects of feedthrough through the board. A microstrip technique is by far the best but not always possible with a double sided board. In this technique, the component side of the board is dedicated to ground plane while signal traces are placed on the solder side.

The AD7836 should have ample supply bypassing located as close to the package as possible, ideally right up against the device. Figure 20 shows the recommended capacitor values of 10 μ F in parallel with 0.1 μ F on each of the supplies. The 10 μ F capacitors are the tantalum bead type. The 0.1 μ F capacitor should have low Effective Series Resistance (ESR) and Effective Series Inductance (ESI), such as the common ceramic types, which provide a low impedance path to ground at high frequencies to handle transient currents due to internal logic switching.

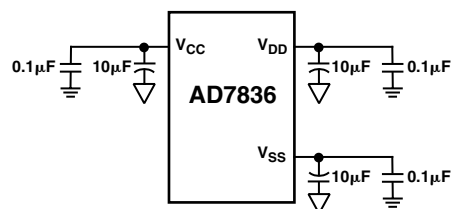


Figure 20. Recommended Decoupling Scheme for AD7836

AD7836

these DACs can be operated with supplies of 0 V and a -5 V, with the V_{DD} pin connected to 0 V and the GND pin connected to -5 V. Now these can be used to provide the negative reference voltages for the $V_{REF(-)}$ inputs on the AD7836. However,

the digital signals driving the DACs need to be level shifted from the 0 V to $+5$ V range to the -5 V to 0 V range. Figure 22 shows a typical application circuit to provide programmable reference capabilities for the AD7836.

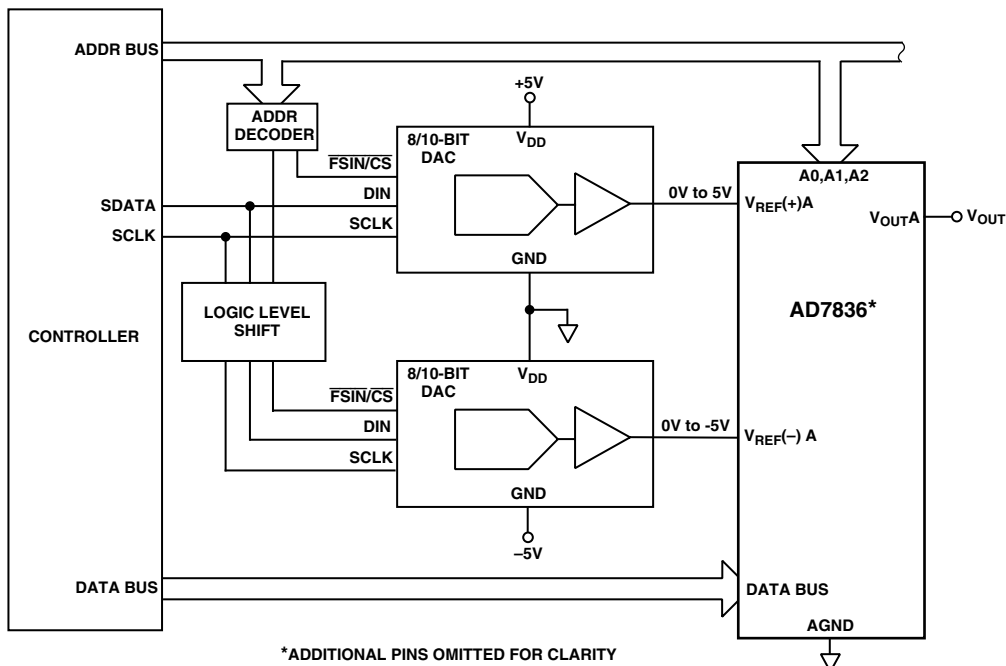


Figure 22. Programmable Reference Generation for the AD7836

OUTLINE DIMENSIONS

Dimensions shown in inches and (mm).

44-Lead MQFP (S-44)

